

WHAT IS CLAIMED IS:

1 1. A semiconductor device comprising:

2 a. a leadframe including a plurality of leads extending therefrom, a first
3 source attach area on a first surface of the leadframe and a first gate attach area, and a second
4 source attach area on a second surface of the leadframe and a second gate attach area;

5 b. at least two dies, a first of which is coupled to the first source and gate
6 attach areas and a second of which is coupled to the second source and gate attach areas;

7 c. a drain connection assembly coupled to a drain region of the first die;

8 and,

9 a body, the body being coupled to the semiconductor device such that a drain

10 region of the second die is exposed.

1 2. A semiconductor device in accordance with claim 1 wherein at least

2 one of the dies is a bumped die.

1 3. A semiconductor device in accordance with claim 2 wherein both dies

2 are bumped dies.

1 4. A semiconductor device in accordance with claim 1 wherein the drain

2 connection assembly comprises a drain clip and a lead rail adjacent an edge of the drain clip.

1 5. A method of making a semiconductor device, the method

2 comprising:

3 providing a leadframe including a plurality of leads extending therefrom, a

4 first source attach area on a first surface of the leadframe and a first gate attach area, and a

5 second source attach area on a second surface of the leadframe and a second gate attach area;

6 bonding a first die to the first source and gate attach areas with solder;

7 reflowing the solder;

8 bonding a second die to the second source and gate attach areas with second

9 solder;

10 bonding a drain connection assembly to a drain region of the second die with

11 third solder;

12 reflowing at least the third solder; and

13 coupling a body to the semiconductor device such that a drain region of the

14 second die is exposed.

